## 1-530743-4 V ACTIVE

#### **AMP**

TE Internal #: 1-530743-4

PCB Mount Header, Right Angle, Board-to-Board, 40 Position, 1.27 mm [.05 in] Centerline, Partially Shrouded, Gold (Au), Through Hole

- Solder

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: PCB Mount Header

PCB Mount Orientation: Right Angle
Connector System: Board-to-Board

Number of Positions: 40
Number of Rows: 2

#### **Features**

#### **Product Type Features**

PCB Connector Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Partially Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly
Configuration Features	

Stackable	No
PCB Mount Orientation	Right Angle
Number of Positions	40
Number of Rows	2

#### **Electrical Characteristics**

Dielectric Withstanding Voltage (Max)	600 VAC	
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## **Body Features**

Primary Product Color	Gray	

#### **Contact Features**

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Contact Mating Area Plating Material Thickness	1.27 μm[50 μin]
Mating Square Post Dimension	.46 mm[.018 in]
	100 μin
Contact Layout	Staggered
Contact Base Material	Brass
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Mating Area Plating Material	Gold (Au)
Contact Type	Pin
Contact Current Rating (Max)	1.5 A
Termination Features	
Rectangular Termination Post & Tail Width	.46 mm[.018 in]
Rectangular Termination Post & Tail Thickness	.23 mm[.009 in]
Termination Post & Tail Length	3.56 mm, 5.08 mm, 6.98 mm, 8.89 mm[.14 in][.2 in][.275 in][.35 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Keyed
Mating Alignment Type  PCB Mount Retention	Keyed Without
PCB Mount Retention	Without
PCB Mount Retention  PCB Mount Alignment	With
PCB Mount Retention  PCB Mount Alignment  Connector Mounting Type	Without With Board Mount
PCB Mount Retention  PCB Mount Alignment  Connector Mounting Type  Mating Alignment	Without With Board Mount
PCB Mount Retention  PCB Mount Alignment  Connector Mounting Type  Mating Alignment  Housing Features	With  Board Mount  With
PCB Mount Retention  PCB Mount Alignment  Connector Mounting Type  Mating Alignment  Housing Features  Housing Material	With  Board Mount  With  LCP (Liquid Crystal Polymer)
PCB Mount Retention  PCB Mount Alignment  Connector Mounting Type  Mating Alignment  Housing Features  Housing Material  Centerline (Pitch)	With  Board Mount  With  LCP (Liquid Crystal Polymer)
PCB Mount Retention  PCB Mount Alignment  Connector Mounting Type  Mating Alignment  Housing Features  Housing Material  Centerline (Pitch)  Dimensions	With  Board Mount  With  LCP (Liquid Crystal Polymer)  1.27 mm[.05 in]
PCB Mount Retention  PCB Mount Alignment  Connector Mounting Type  Mating Alignment  Housing Features  Housing Material  Centerline (Pitch)  Dimensions  Row-to-Row Spacing	With  Board Mount  With  LCP (Liquid Crystal Polymer)  1.27 mm[.05 in]  3.81 mm[.15 in]
PCB Mount Retention  PCB Mount Alignment  Connector Mounting Type  Mating Alignment  Housing Features  Housing Material  Centerline (Pitch)  Dimensions  Row-to-Row Spacing  Stack Height	Without With  Board Mount With  LCP (Liquid Crystal Polymer) 1.27 mm[.05 in]  3.81 mm[.15 in] 15.24 mm[.6 in]
PCB Mount Retention  PCB Mount Alignment  Connector Mounting Type  Mating Alignment  Housing Features  Housing Material  Centerline (Pitch)  Dimensions  Row-to-Row Spacing  Stack Height  PCB Thickness (Recommended)	Without  With  Board Mount  With  LCP (Liquid Crystal Polymer)  1.27 mm[.05 in]  3.81 mm[.15 in]  15.24 mm[.6 in]  .05 – .07 mm[.054 – .07 in]
PCB Mount Retention PCB Mount Alignment Connector Mounting Type Mating Alignment Housing Features Housing Material Centerline (Pitch)  Dimensions Row-to-Row Spacing Stack Height PCB Thickness (Recommended) Connector Height	Without  With  Board Mount  With  LCP (Liquid Crystal Polymer)  1.27 mm[.05 in]  3.81 mm[.15 in]  15.24 mm[.6 in]  .05 – .07 mm[.054 – .07 in]
PCB Mount Alignment  Connector Mounting Type  Mating Alignment  Housing Features  Housing Material  Centerline (Pitch)  Dimensions  Row-to-Row Spacing  Stack Height  PCB Thickness (Recommended)  Connector Height  Usage Conditions	With  Board Mount  With  LCP (Liquid Crystal Polymer)  1.27 mm[.05 in]  3.81 mm[.15 in]  15.24 mm[.6 in]  .05 – .07 mm[.054 – .07 in]  7.87 mm[.31 in]



Assembly Process Feature	None
Circuit Application	Power & Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	6
Packaging Method	Package

## **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Not Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2024 (240) SVHC > Threshold: Pb (4% in Plating) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Not Yet Reviewed for halogen content
Solder Process Capability	Wave solder capable to 265°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Customers Also Bought

















## **Documents**

#### **Product Drawings**

MINI BOX PIN HDR ASY 40 POS

English

#### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_1-530743-4\_V.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-530743-4\_V.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-530743-4\_V.3d\_stp.zip

English

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